

## **Technical Data Sheet**

MODEL NO: 193UR/UYG4-JH 1.6\*0.8mm Chip LEDs

### Features:

- Package in 8mm tape on 7" diameter reel
- Compatible with automatic placement equipment
- Compatible with reflow solder process

### Applications:

- Indicators
- Automotive: backlighting in dashboard and switch
- Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaInP	Red	
		Water Clear
AlGaInP	Yellow-Green	

### Electrical/Optical Characteristics(Ta=25°C)

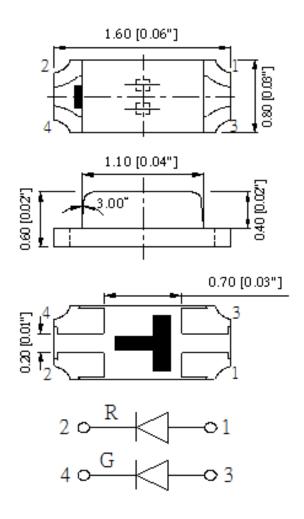
Parameter	Test	Symbol		Value			l lmit
	Condition			Min	Тур	Max	Unit
Spectral half bandwidth	IF=20mA	Δλ	R		20		- nm
			G		20		
Dominant wavelength	IF=20mA	λD	R	620		630	- nm
Dominant wavelength			G	565		576	
Forward valtage	IF=20mA	VF	R	1.8		2.4	V
Forward voltage			G	1.8		2.4	
Luminous intensity	IF=20mA	lv	R	80	110	200	- mcd
			G	32	50	80	
Viewing angle at 50% lv	IF=10mA	2 <i>0</i> 1/2	-	-	120	ı	Deg
Reverse current	V <sub>R</sub> =5V	lr	-	-	ı	10	μΑ

### Absolute Maximum Ratings(Ta= $25^{\circ}$ C)

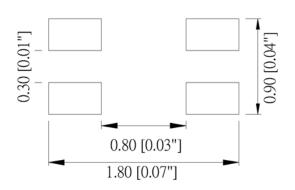
Parameter	Symbol		Value	Unit	
Power dissipation	Pd	R	75	mW	
	Pu	G	111		
Forward current	lF		30	mA	
Reverse voltage	Vr		5	V	
Operating temperature range	Тор		-40 ~+80	$^{\circ}\!\mathbb{C}$	
Storage temperature range	Tstg		-40 ~+85	$^{\circ}\!\mathbb{C}$	
Peak pulsing current (1/8 duty f=1kHz)	lfP		72	mA	



# PACKAGING DIMENSIONS (mm):



## RECOMMEND PAD LAYOUT



### **Precautions For Use:**

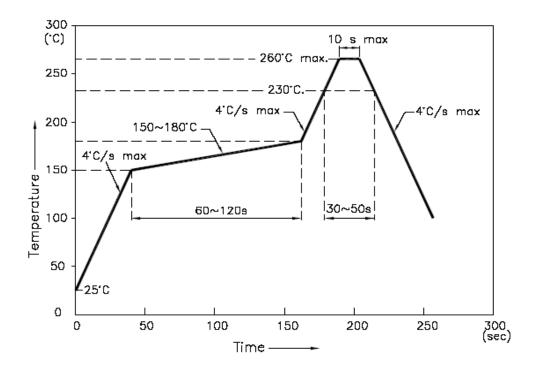
### Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

#### Storage

- 1. The operation of temperature and R.H. are :  $5^{\circ}$ C  $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}\text{C}\pm5^{\circ}\text{C}$  for 15hrs.

### ■ Reflow Temp/Time



#### NOTES:

- 1. We recommend the reflow temperature  $245\,^{\circ}\text{C}(\pm 5\,^{\circ}\text{C})$ .the maximum soldering temperature should be limited to  $260\,^{\circ}\text{C}$ .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

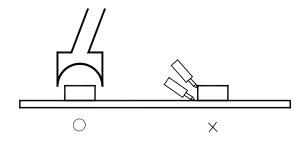


### ■Soldering iron

Basic spec is  $\leq$  5sec when 260°C. If temperature is higher, time should be shorter (+10°C  $\rightarrow$  -1sec ). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

### **■**Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \, solder etc.